

LAYER STACKUP

Top
F.Silkscreen Top silkscreen (White, Direct Printing)
F.Paste Top paste
F.Mask Top mask (Green, 0.02mm, Solder Resist, Er=3.8)
L1 (Sig,PWR) Copper 0.035mm

Dielectric 1 Prepreg
1/1 FR4 natural 0.0994mm
3313 RC57% 4.2mil, Er=4.1, LossTg=0.02

L2 (GND) Copper 0.0152mm

Dielectric 2 Core
1/1 FR4 natural 0.55mm
0.55mm H/Hwithout copper, Er=4.41, LossTg=0.02

L3 (Sig,PWR) Copper 0.0152mm

Dielectric 3 Prepreg
1/1 FR4 natural 0.1088mm
2116 RC54% 4.9mil, Er=4.16, LossTg=0.02

L4 (Sig,PWR) Copper 0.0152mm

Dielectric 4 Core
1/1 FR4 natural 0.55mm
0.55mm H/Hwithout copper, Er=4.41, LossTg=0.02

L5 (GND) Copper 0.0152mm

Dielectric 5 Prepreg
1/1 FR4 natural 0.0994mm
3313 RC57% 4.2mil, Er=4.1, LossTg=0.02

L6 (Sig,PWR) Copper 0.035mm
B.Mask Bottom mask (Green, 0.02mm, Solder Resist, Er=3.8)
B.Paste Bottom paste
B.Silkscreen Bottom silkscreen (White, Direct Printing)

Finish Option ENIG
Impedance Controlled

PCB AREA

